

PATENT APPLICATION ATTORNEY DOCKET NO. 10007137-1

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

ART UNIT: 2655

EXAMINER: Nabil Z. Hindi

APPLICANT: Gibson et al.

SERIAL NO.: 09/865,940

FILED: May 25, 2001

CONFRM. NO.: 6644

FOR: DATA STORAGE MEDIA UTILIZING DIRECTED LIGHT BEAM AND NEAR-FIELD

OPTICAL SOURCES

RESPONSE/DECLARATION

CERTIFICATE OF MAILING UNDER 37 C.F.R. § 1.8

DATE OF DEPOSIT: June 10, 2004

I hereby certify that this paper or fee (along with any paper or fee referred to as being attached or enclosed) is being deposited with the United States Postal Service with sufficient postage as first class mail on the date indicated above and is addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-14507

Vaughn W. North

DECLARATION OF GARY A. GIBSON UNDER 37 C.F.R. § 1.131

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Technology Center 2600

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

- I, Gary A. Gibson, declare as follows:
- 1. I am a named co-inventor in the above-captioned application and of the subject matter described and claimed therein.
- 2. It is my understanding that the claims in the above-recited patent application have been rejected in view of U.S. Patent No. 6,473,388 filed August 31, 2000 and issued to me, Gary A. Gibson, on October 29, 2002 (hereinafter the Gibson 388 Patent).

- 3. The invention as described and claimed in the above-reference patent application, Serial No. 09/865,940, filed May 25, 2001, entitled: "Data Storage Media Utilizing Directed Light Beam and Near-Field Optical Sources," ("Present Application") was conceived and reduced to practice by the inventors named therein prior to August 31, 2000.
- 4. Exhibit 1, attached hereto, dated March 29, 1995, is a copy of a page from my notebook. Because it is a little difficult to read, its contents are stated again here, as follows: "Near-Field Optical Version of Diode Approach Could use near-field optical source such as used in NSOM as read/write head for any of "diode" approaches. Advantage: Penetration depth of light can be greater than that of low E electrons fewer problems w/ surfaces (recombination, etc.) Disadvantage: Not much light out of small aperture. NSOM sources (lasers, etc.), expensive and bulky. Need to stay fairly close to medium (gap < bit size)."
- 5. The lab notebook page shown in Exhibit 1 is evidence of conception of the invention in the Present Application prior to August 31, 2000, particularly with respect to the diode embodiment shown therein.
- 6. Exhibit 2, attached hereto and dated August 30, 2000, contains a copy of invention disclosure that I and the other inventor in the Present Application, Alison Chaiken, prepared and submitted to our employer, Hewlett Packard.
- 7. The document in Exhibit 2 is evidence of conception and reduction to practice of the invention in the Present Application prior to August 31, 2000.
- 8. I declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful, false statements and the like so made are

punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful, false statement may jeopardize the validity of the application or any patent issuing thereon.

Declared this $\frac{9+4}{2}$ day of June, 2004.

Gary A. Gibson



Exhibit 1 to Declaration of Gary A. Gibson

HPL 1814- 13

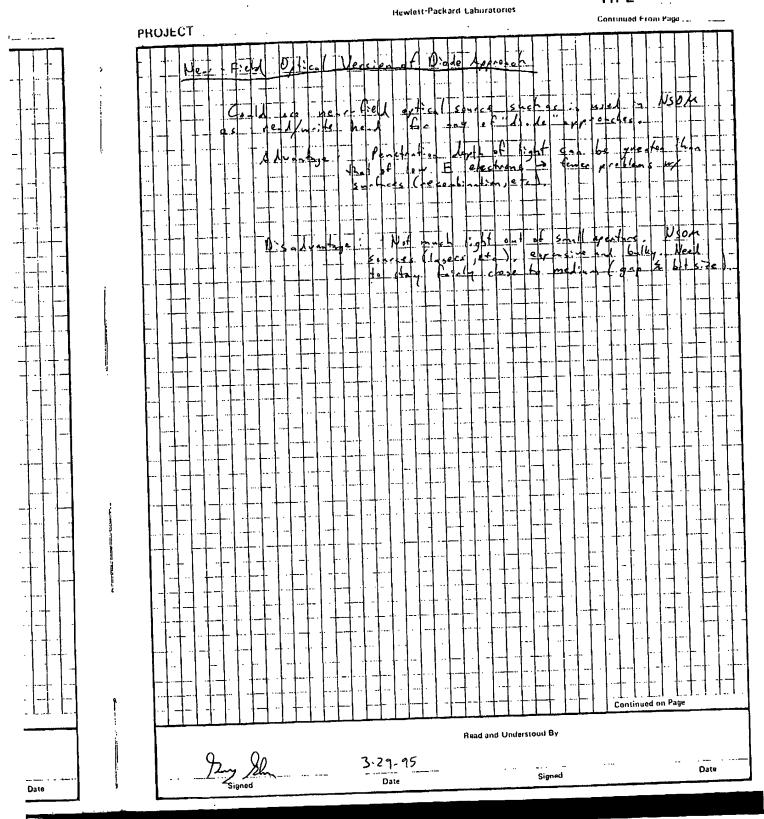




Exhibit 2 to Declaration of Gary A. Gibson

HEWLETT*	INVENTION DIS O	SURE 9/12/1			
PACKARD	PDNO 10007137	7 - 11010			GE ONE OF
		DATE RCVD			TORNEY
Instructions: The information contained in this document is COMPANY CONFIDENTIAL and may not be disclosed to others without prior authorization. Submit this disclosure to the HP Legal Department as soon as possible. No patent protection is possible until a patent application is authorized, prepared, and submitted to the Government.					
Descriptive Title of Data Storage Med	or Invention: lium Utilizing Near-Field Optica	d Source			
Name of Project:	num ounting wear relu opuce	Jource			
Atomic Resolution	n Storage				
Product Name or					
Was a description of No.	of the invention published, or are	you planning to publish? If so,	the date(s) and publica	tion(s):	
Was a product inclu No.	uding the invention announced, o	ffered for sale, sold, or is such a	activity proposed? If so	, the date(s) an	d location(s):
Was the invention of No.	disclosed to anyone outside of H	P, or will such disclosure occur?	If so, the date(s) and r	name(s):	
	fany of the above situations will occur wil	hin 3 months, call your IP attorney or th	e Legal Department now at 1	-898-4919 or 970-8	98-4919.
Was the invention of	described in a lab book or other re	ecord? If so, please identify (lab	book #, etc.)		
Yes. Lab book #18	14.				
Was the invention b	ouilt or tested? If so, the date:				
No.					
Was this invention r	nade under a government contra	ct? If so, the agency and contra	act number:		
No.					
A. Prior solut B. Problems C. Advantage	be signed and dated by the signed and dated by the signed and dated by the sions and their disadvantages (if a solved by the invention. es of the invention over what has n of the construction and operation	inventor(s) and witness(es). Ivailable, attach copies of produ been done before.	ict literature, technical a	articles, patents	, etc.).
samples; g	graphs; flowcharts; computer listi	nas: test results: etc.)			
Signature of Invent	tor(s): Pursuant to my (our) emp	loyment agreement, I (we) subr	nit this disclosure on thi	is date: [A - 9	4st 30, 2000].
268872 Gary (Gibson	Day Sh	957 2425	011.00	1071 400
	Name	Signature	857-2125 Telnet	2U-20 Mailstop	ISTL-ASD Entity Acronym
, ,	_	oignature 1	i cillet	Manarob	Enuty Acronym
	Chaiken	Wi Chita	236-2231	2U-20	ISTL-ASD
Employee No. 1	Name	Signature	Telnet	Mailstop	Entity Acronym
Employee No.	Name	Signature	Telnet	Mailstop	Entity Acronym
• •	Name ore than four inventors, include a	Signature dditional information on another	Telnet r copy of this form and a	Mailstop attach to this do	Entity Acronym

HEWLETT INVENTION DIS	OSUBE		
		COMPANY CONFIDE . FIAL	PAGE _2 OF _4
Signature of Witness(es): (Please try to ob	stain the signature of the person(s) to	o whom invention was first disclosed.)	
The invention was first explained to, and	a understood by, me (us	s) on this date: 4p2 . 14	Date of Signature
	Signature	,	
CHUNCY CHING YANG			8/30/2000
Full Name	Signature		Date of Signature
		`	
Inventor & Home Address Information	n: (If more than four inventors, inc	clude addl. information on a copy of this form of	attach to this document)
Inventor's Full Name			
Con Alfred O'h			
Gary Alfred Gibson Street			
119 Seale Avenue			
City		State	Zip
Palo Alto		CA	94301
Do you have a Residential P.O. Address? P.O. BOX	City	State	
Greeted as (nickname, middle name, etc.)		Citizenship	
Gary		U.S.A.	
Inventor's Full Name			
Alison Chaiken			
Street			
A . 51			
On file			
City		State	Zip
Do you have a Residential P.O. Address? P.O. BOX	City	State	Zip
Greeted as (nickname, middle name, etc.)		Citizenship	
Alison		U.S.A.	
Inventor's Full Name			
Street			
City		State	Zip
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Greeted as (nickname, middle name, etc.)		Chibi-	
		Citizenship	
Inventor's Full Name			
Street			
Cib.			
City		State	Zip
Do you have a Residential P.O. Address? P.O. BOX	City	State	Zip
Greeted as (nickname, middle name, etc.)		Citizenship	

Description of Invention: Please preserv. records of the invention and attach additional pag. or the following. Each additional page should be signed and dated by the inventor(s) and witness(es).

A. Prior solutions and their disadvantages (if available, attach copies of product literature, technical articles, patents, etc.).

In conventional rewriteable optical recording devices such as CD-RW and DVD-RW drives, bits are written by using lasers to reversibly change the optical reflectivity of a storage medium. The diffraction-limited spot size of the lasers sets a lower bound to the size of the bits that can be written. Currently, a number of groups are working to increase the areal storage density of optical recording devices by using near-field light sources. These near-field sources use evanescent light emitted through a small aperture to circumvent the diffraction limit. In a typical embodiment, light from a laser is emitted through an aperture (that has a diameter less than the wavelength of the light) at one end of the laser cavity. Alternatively, the light from a laser is coupled into a fiber optic cable. The end of the cable furthest from the laser tapers down to a small diameter and is coated with a metal. This coated, tapered fiber forms a waveguide for the laser light. The tapered end of the fiber contains a small hole (diameter< wavelength of the light) that constitutes a near-field light source. In these approaches, some of the near-field light that is incident on the storage medium is reflected back into the laser cavity through the small aperture in the laser or the fiber-optic cable. This reflected light causes a change in the output power of the laser that can be monitored to detect changes in reflectivity and, thereby, the presence of bits. A disadvantage to this bit detection technique is the tiny amount of light that is reflected back into the laser cavity and the correspondingly small changes to the output power of the laser. To read very small bits it is desirable to have a technique capable of producing larger signals (and a larger ratio of signal to noise). The present invention provides this technique.

It has also been proposed (patent # 5,557,596) that an electron beam can be used to read and write data on the surface of a diode. It is desirable to use low energy electrons in this technique so as to avoid problems with dielectric breakdown, field-emission from undesirable locations, and the need for relatively large and expensive power supplies. However, low energy electrons have very short penetration depths. Thus, if low energy electrons are used, this technique is highly susceptible to the condition of the surface of the storage medium. In many cases this has an adverse effect on the functioning of this technique. The present invention is capable of circumventing this problem.

The necessity of getting the low-energy electrons into the storage layer also limits device designs, in that only very thin la yers may be present on top of the storage media. Thus, an optically transparent conducting electrode could not be placed on top of the storage layer in an electron-beam-addressed memory, as an optically transparent electrode would still block electrons. If a conducting electrode on top of the storage area is desirable, it will in electron-beam-read back schemes limit the area of the device that can be used for storage. In addition, the stability and cyclability of a storage device using electron-readback may be limited by the mechanical and thermal properties of the free surface of the storage medium. Only very thin protective cladding layers can be used with the electron-beam-addressing scheme, as once again these layers would prevent access by low energy electrons.

B. Problems solved by the invention.

This invention addresses the <u>small readback signals obtained in near-field optical recording devices</u> from very small bits. It also addresses the issues caused by the short penetration depth of low energy electrons in the devices described in patent # 5,557,596.

Advantages of the invention over what has been done before.

The present invention gives larger readback signals in near-field optical recording devices. Also, it can make use of storage materials that don't necessarily exhibit large changes in reflectivity between their written and unwritten states. This new invention is not as susceptible to surface conditions as the devices described in patent # 5,557,596. It also has more design flexibility and possibly better robustness than the electron-beam readback devices described in patent # 5,557,596.

D. Description of the construction and operation of the invention (include appropriate schematic, block, & timing diagrams; drawings; samples; graphs; flowcharts; computer listings; test results; etc.)

In one embodiment, the storage medium is a diode. One layer of the diode is a material that can be changed between two or more states using a near-field optical source. We will call this the storage layer. The storage layer is in contact with another material or materials with which it forms a diode. The diode can be of any type that provides a built-in field for separating charge carriers. For example, the diode can be a pn-junction, pin-junction, or Schottky barrier depending on the material(s) used. A bit is written by locally altering the state of the storage layer with the aid of a near-field optical source. The different states of the storage material must be such that they provide a contrast in the bit detection ("read") mechanism described below. In one embodiment, the storage layer is a phase-change material similar to those currently used in optical recording. These materials can be reversibly changed from crystalline to amorphous by applying heat with the right temperature vs. time profile. The near-field optical source can be used for this purpose. The storage layer need not be a "phase-change" material, however. Any material that can be locally changed from one state to another state by means of a near-field optical source can be used. The near-field source need not operate in isolation to affect the transition from one state to another. It can also be used in conjunction with some other energy source. For example a resistive heater or applied electric field could be used to bias a large area of the storage medium while the near-field source locally affected a phase-change.

To read a bit, a near-field optical source is used to locally excite charge carriers in one of the layers of the diode. If carriers are excited in the storage layer, the number of carriers created (the "generation efficiency") will depend on the state of the storage layer in the region where photons

from the near-field source are incident. The present that determine the generation efficiency includes the storage layer. Some fraction of the generated carriers of one sign (enter electrons or holes) will be swept across the diode interface under the influence of the built-in field and any applied field. The current that results from carriers passing across the diode interface can be monitored to determine the state of the area on which the read photons are incident. The fraction of generated carriers that makes it across the diode interface (the "collection efficiency") is dependent upon the recombination rate in and around the area on which the read photons are incident, the effect of the bit on the built-in fields, etc. Thus, contrast in the current generated across the diode by the read photons can depend on both the local generation efficiency and the local collection efficiency. Both of these factors are influenced by the state of the region upon which the read photons are incident.

The generation and collection efficiency for carriers generated in the Layer Adjacent to the Storage Layer (LASL) can also be influenced by the presence of a bit in the neighboring storage area. Carriers can be generated in the LASL if it is the layer closest to the near-field source. Alternatively, carriers can be generated in the LASL, even if the storage layer is closest to the source, if the storage layer is sufficiently transparent to the read beam. In this case, the number of carriers generated in the LASL will depend on the number of read photons that make it through the storage layer. Thus, contrast in the read signal can be obtained by using the storage layer as a state-sensitive variable absorber. In this case, the storage layer may not itself form part of the diode structure. The transmission of this absorber can depend upon whether the beam is passing through a written or unwritten region. Alternatively, contrast in the generation rate of carriers in the LASL can arise due to differences in the electric field in the LASL due to the presence or absence of a bit in the neighboring storage layer. One way in which an electric field can influence the generation rate for free carriers is by reducing the geminate recombination rate. The collection efficiency for carriers generated in the LASL can be also be influenced by the presence or absence of a bit in the neighboring storage layer via changes in the electric field. In addition, this collection efficiency can be influenced by changes in recombination rate due to the presence or absence of a bit in the neighboring storage layer (e.g. an amorphous bit could locally increase the interface recombination velocity at the storage layer/LASL interface). Again, differences in the collection efficiency of carriers created by the read beam provide contrast in the signal current generated across the diode.

It may be advantageous to cover the storage layer with a protective layer. During the write process, this protective layer could help to prevent chemical changes such as oxidation or thermomechanical changes such as bump or pit formation. It is possible that the LASL could serve as the protective layer as long as it is thin enough to allow writing of small bits. The protective layer may be merely a passivation layer, or it may be a conducting transparent electrode that is used to collect the photogenerated carriers.

The presence of electrodes on both the top and bottom surfaces of the storage layer and a possible LASL may offer advantages in device design. For example, uniform top and bottom electrodes will enhance the uniformity of the biasing field formed between the electrode and the storage layer. A back electrode could be present either on the side of the substrate opposite the optical sources (if a conducting substrate is used), or the back electrode could be on top of the substrate (if an electrically isolated substrate is used that provides mechanical support, but is not part of the electrical device per se. A top electrode could, in an optical access scheme, cover the entire top surface of the device.

It may be advantageous to cover the storage layer with a layer that enhances the thermal properties of the overall storage medium. E.g., if the storage layer is a phase-change material then it may be desirable for it to be in contact with a layer that aids in thermal quenching when trying to amorphize it. Alternatively or in conjunction with a cover layer it may be desirable to have a layer underneath the storage layer or LASL that improves thermal properties such as the ability to quench (and amorphize) the storage layer. An underlayer may also enhance the robustness of the device by preventing interdiffusion between the storage layer and the substrate material, or by discouraging delamination or dewetting of the storage layer (or LASL) from the substrate.

It may be advantageous to cover the storage layer with a layer that enhances optical properties such as an anti-reflection coating. For example, this could be used to increase the amount of light from the near field source that is absorbed in the storage layer or LASL. Alternatively, or in conjunction with a cover layer, a layer underneath the storage layer or LASL could be used to enhance the optical properties.

By monitoring the collection efficiency of a diode structure, it may be possible to control the separation of a plate containing the storage layer and diode structure from the optical sources. Alternatively, it may be possible to control this separation by monitoring the light reflected back into the near-field optical source, or by using a combination of both techniques. It may be advantageous to provide tracking and sector reference marks on the media layer surface by providing areas of contrasting reflectivity or diode collection efficiency.

When reading back signals from the media, it may be advantageous to use the near-field optical source in a constant flux mode, with the light source on steadily and the sampling window provided by translation or rotation of the media underneath the source. Alternatively, it might be preferable to pulse the optical source or otherwise modulate it in order to use a phase- and/or frequency-selective signal-to-noise enhancement technique in the diode signal amplifier electronics.



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OPTICAL SOURCES

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DATE OF DEPOSIT: June 10, 2004

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Vaughn W. North

DECLARATION OF ALISON CHAIKEN UNDER 37 C.F.R. § 1.131

Commissioner for Patents P.O. Box 1450 Arlington, VA 22313-1450

- I, Alison Chaiken, declare as follows:
- 1. I am a named co-inventor in the above-captioned application and of the subject matter described and claimed therein.
- 2. It is my understanding that the claims in the above-recited patent application have been rejected in view of U.S. Patent No. 6,473,388 filed August 31, 2000 and issued to Gary A. Gibson, on October 29, 2002 (hereinafter the Gibson 388 Patent).

UNSIGNED COPY – SIGNED ORIGINAL IN TRANSIT

- 3. The invention as described and claimed in the above-reference patent application, Serial No. 09/865,940, filed May 25, 2001, entitled: "Data Storage Media Utilizing Directed Light Beam and Near-Field Optical Sources," ("Present Application") was conceived and reduced to practice by the inventors named therein prior to August 31, 2000.
- 4. Exhibit 1, attached hereto and dated June 27, 2000, is a set of slides used in a presentation that I gave that contains information about a reduction to practice of the invention in the Present Application. Slide 13 in Exhibit 1 shows some bits recorded in a phase-change material (In2Se3) using a laser light beam. The image was created in connection with the photoconductive readback structure that is one of the embodiments shown in the Present Application.
- 5. The presentation slides shown in Exhibit 1 are evidence of conception and reduction to practice of the invention in the Present Application prior to August 31, 2000, particularly with respect to the photoconductive readback embodiment shown therein.
- 6. Exhibit 2, attached hereto and dated August 30, 2000, is a copy of an invention disclosure that I and the other inventor in the Present Application, Gary A. Gibson, prepared and submitted to our employer, Hewlett Packard.
- 7. The document in Exhibit 2 is further evidence of conception and reduction to practice of the invention in the Present Application prior to August 31, 2000.
- 8. I declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful, false statements and the like so made are

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punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States			
Code, and that such willful, false statement may jeopardize the validity of the application or any			
patent issuing thereon.			
Declared this day of June, 2004.			
Alison Chaiken			



Exhibit 1 to Declaration of Alison Chaiken

Media Writing Experiments and Electrical Characterization

Alison Chaiken Advanced Storage Department June 27, 2000

- Electrical experiments: good transport properties in In₂Se₃
- Writing experiments: problems, success?
- Looking ahead to cyclability challenge



Purpose of Transport Experiments

- Track media film quality
- Select devices for more sophisticated measurements
- Provide parameters for device modeling
- 3 types of experiments:
- Hall to measure carrier density, mobility
- AC photoconductivity to measure frequency response
- DC photocurrent to measure device performance.



First Successful Hall Measurements

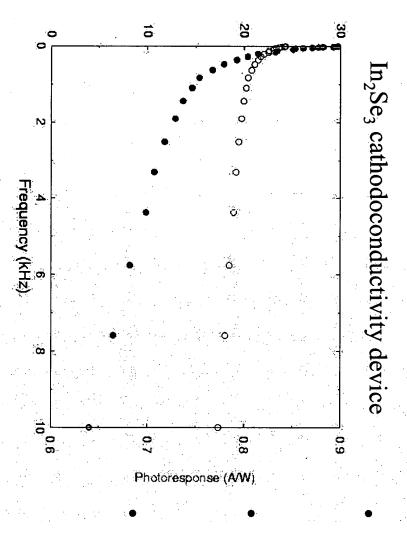
on $ln_2 Se_3$

- Mobilities in the range 10 to 40 cm²/V-s.
- Carrier densities 10¹² to 10¹⁴ cm⁻³, always n-type.
- Resistivities in the range of 10^3 to 10^5 ohm-cm:
- may be too resistive for diodes;
- good range for cathodoconductivity devices;
- doping may lower resistivity (Te addition experiments).
- Correlation with deposition parameters is weak.



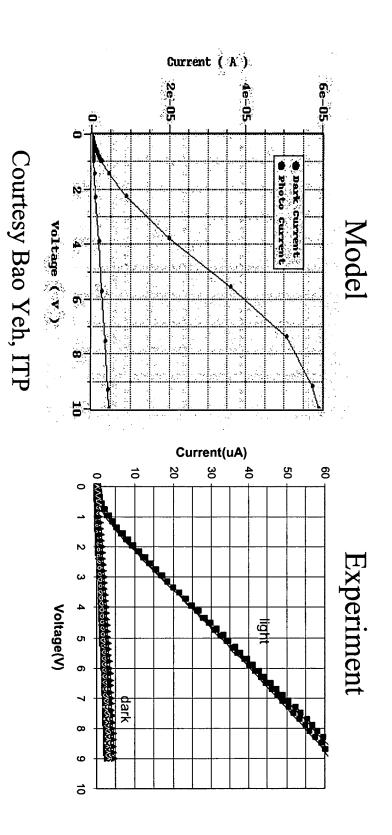
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Large Photoeffect in In₂Se₃



- Frequency dependence and magnitude indicate electronic origin.
- Predict large cathodoconductivity response.
- U. Nantes reports larger photoconductivity in Te-doped In₂Se₃ than in undoped In₂Se₃.

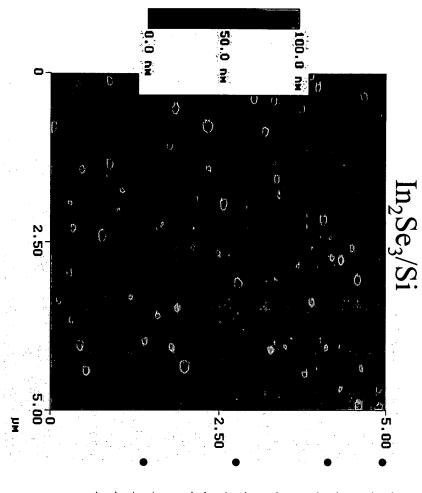
Modeling will help predict device performance





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Grain size and transport properties



- Hall devices are on SiO₂.
- Films have <= 100 nm grain size.
- Films on Si can have >=1μm grain size.
- Media films on diodes have better properties?



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Enlarge grain size by annealing?

- AFM shows post-annealing films does not enlarge grain
- needs quantitative x-ray study.
- mert atmosphere, even capped films. Hall devices consistently more resistive after annealing in
- Films become more intrinsic?
- Se loss at grain boundaries?
- Oxidation at grain boundaries?



Grain size and transport properties

- charge regions at grain boundaries. Film electrical properties may be dominated by space-
- Grain boundary engineering an essential part of making devices work.
- New experiments:
- Se cap layer to discourage composition changes;
- hydrogen plasma annealing to passivate dangling bonds.



Writing Amorphous Marks on

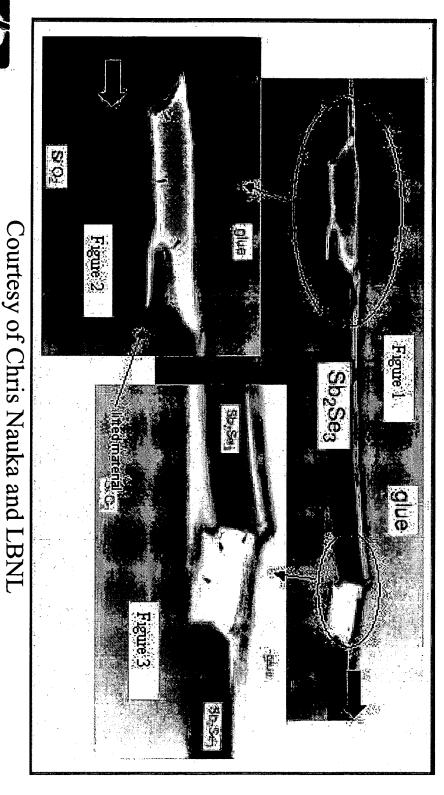
In₂Se₃ Media

- In some sense, a trivial task.
- However, problems may arise:
- delamination of film from substrate or cracking;
- decomposition or oxidation of In₂Se₃;
- diffusion of excess Se;
- sublimation at a temperature below melting.
- Reliably identifying the amorphous phase is another problem.



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Writing Amorphous Spots on Sb2Se3 Successful



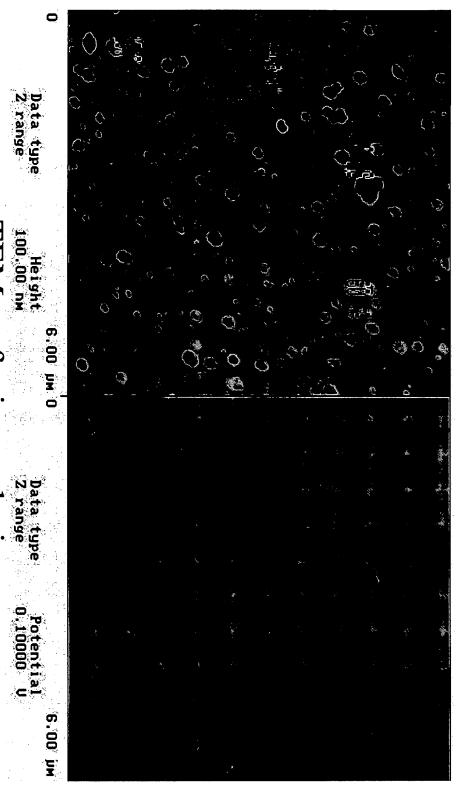




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Marking Films -- or Destroying Them?

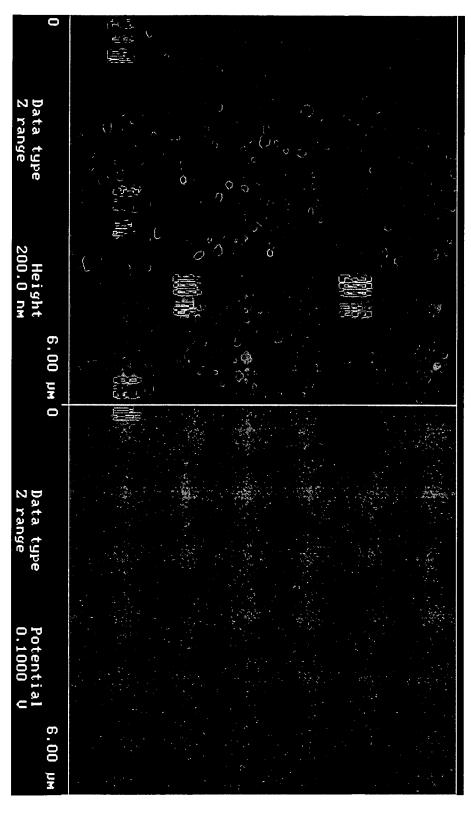
170 nm thick In₂Se₃ with µm-scale grains on Si



TEM so far inconclusive.

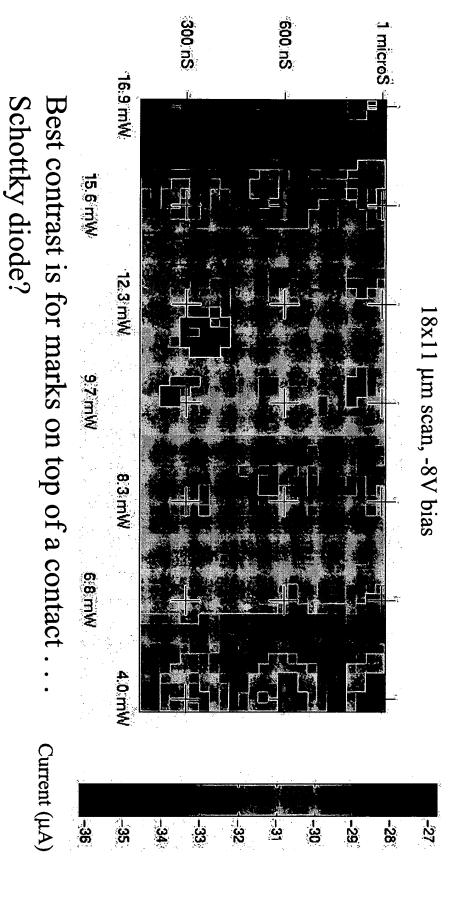
Small-grained films survive marking better

400 nm thick In₂Se₃ with 100 nm grains on SiO₂



Thanks to G. Burward for improved sample fixturing.

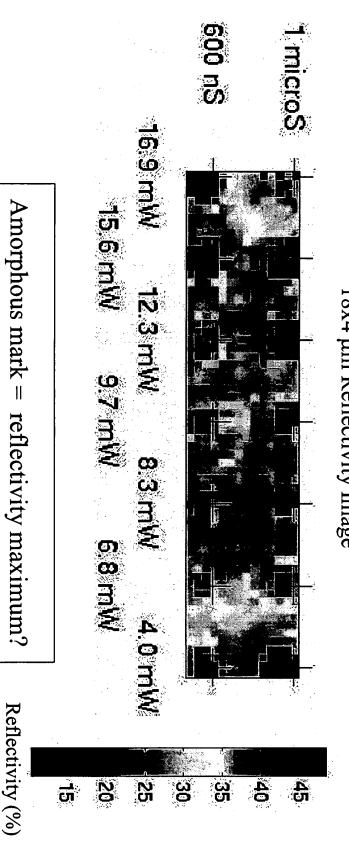
Lasers Marks are Visible in Photocurrent Image



Optical system built by Henryk Birecki.

Plenty of Questions Remain

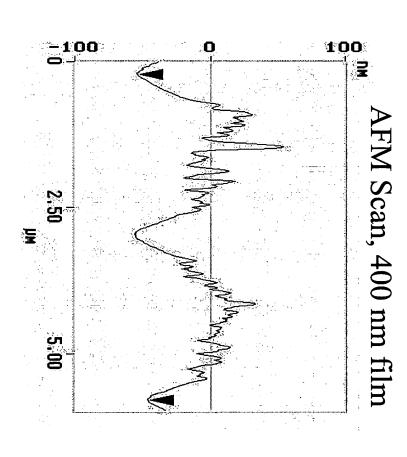
18x4 μm Reflectivity Image





Plenty of Ouestions Remain

- Marks are noticeably smoother than background.
- In In₂Se₃, laser marks are always depressions.
- Absorption length of 488 nm light about 40 nm, similar to depth of depressions.





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Future Work

- Correlate grain size and film texture to transport properties. (Y. Matsushita, SEED)
- Work with ITP to determine whether writing causes compositional changes.
- (MSB) to improve laser tester. Work with Gary Ashton and Mauricio Huerta
- Begin overwrite studies.
- Write amorphous marks on diodes.



Conclusions

- AFM, optical studies suggest amorphous spot writing has been achieved.
- Successful readback of laser marks on cathodoconductivity device.
- Transport properties of In₂Se₃ films are encouraging, possibly good enough.
- Cyclability remains an open question.





Exhibit 2 to Declaration of Alison Chaiken

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HEWLETT*	INVENTION DIS	OSURE 9/10/4		PAGE ONE OF
<u> </u>	PDNO 1000113	DATE RCVD		ATTORNEY 77/
authorized, prepar	red, and submitted to the Gov	his document is COMPANY CONF Legal Department as soon as possib vernment.	IDENTIAL and may not be le. No patent protection is p	disclosed to others without prior possible until a patent application is
Descriptive Title		- H 1 O		
Name of Project:	dium Utilizing Near-Field Op	oucai Source		
Atomic Resolution				
Product Name or	Number:			
Was a description No.	of the invention published, or	r are you planning to publish? If so, the	ne date(s) and publication(s):	
Was a product incl No.	uding the invention announce	ed, offered for sale, sold, or is such ac	tivity proposed? If so, the da	ate(s) and location(s):
Was the invention No.	disclosed to anyone outside o	of HP, or will such disclosure occur?	If so, the date(s) and name(s	s):
Mas the invention	f any of the above situations will occ	cur within 3 months, call your IP attorney or the	Legal Department now at 1-898-491	19 or 970-898-4919.
Yes. Lab book #18		ner record? If so, please identify (lab b)OOK #, etc.)	
		,		
	built or tested? If so, the date	3 :		
No.				
	made under a government co	ontract? If so, the agency and contract	et number:	
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Description of Inv	ention: Please preserve all r	records of the invention and attach ad	ditional pages for the following	ng. Each additional page should
A. Prior solu	tions and their disadvantages	y the inventor(s) and witness(es). s (if available, attach copies of produc	t literature, technical articles	natents etc.)
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Inventor & Home Address Information: (If	more than four inventors, inclu	ude addl. information on a copy of this for	m & attach to this document
Inventor's Full Name	· · · · · · · · · · · · · · · · · · ·	,	
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119 Seale Avenue			
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Description of Invention: Please preserv. records of the invention and attach additional pag. or the following. Each additional page should be signed and dated by the inventor(s) and witness(es).

A. Prior solutions and their disadvantages (if available, attach copies of product literature, technical articles, patents, etc.).

In conventional rewriteable optical recording devices such as CD-RW and DVD-RW drives, bits are written by using lasers to reversibly change the optical reflectivity of a storage medium. The diffraction-limited spot size of the lasers sets a lower bound to the size of the bits that can be written. Currently, a number of groups are working to increase the areal storage density of optical recording devices by using near-field light sources. These near-field sources use evanescent light emitted through a small aperture to circumvent the diffraction limit. In a typical embodiment, light from a laser is emitted through an aperture (that has a diameter less than the wavelength of the light) at one end of the laser cavity. Alternatively, the light from a laser is coupled into a fiber optic cable. The end of the cable furthest from the laser tapers down to a small diameter and is coated with a metal. This coated, tapered fiber forms a waveguide for the laser light. The tapered end of the fiber contains a small hole (diameter< wavelength of the light) that constitutes a near-field light source. In these approaches, some of the near-field light that is incident on the storage medium is reflected back into the laser cavity through the small aperture in the laser or the fiber-optic cable. This reflected light causes a change in the output power of the laser that can be monitored to detect changes in reflectivity and, thereby, the presence of bits. A disadvantage to this bit detection technique is the tiny amount of light that is reflected back into the laser cavity and the correspondingly small changes to the output power of the laser. To read very small bits it is desirable to have a technique capable of producing larger signals (and a larger ratio of signal to noise). The present invention provides this technique.

It has also been proposed (patent # 5,557,596) that an electron beam can be used to read and write data on the surface of a diode. It is desirable to use low energy electrons in this technique so as to avoid problems with dielectric breakdown, field-emission from undesirable locations, and the need for relatively large and expensive power supplies. However, low energy electrons have very short penetration depths. Thus, if low energy electrons are used, this technique is highly susceptible to the condition of the surface of the storage medium. In many cases this has an adverse effect on the functioning of this technique. The present invention is capable of circumventing this problem.

The necessity of getting the low-energy electrons into the storage layer also limits device designs, in that only very thin la yers may be present on top of the storage media. Thus, an optically transparent conducting electrode could not be placed on top of the storage layer in an electron-beam-addressed memory, as an optically transparent electrode would still block electrons. If a conducting electrode on top of the storage area is desirable, it will in electron-beam-read back schemes limit the area of the device that can be used for storage. In addition, the stability and cyclability of a storage device using electron-readback may be limited by the mechanical and thermal properties of the free surface of the storage medium. Only very thin protective cladding layers can be used with the electron-beam-addressing scheme, as once again these layers would prevent access by low energy electrons.

B. Problems solved by the invention.

This invention addresses the <u>small readback signals obtained in near-field optical recording devices</u> from very small bits. It also addresses the issues caused by the <u>short penetration</u> depth of low energy electrons in the devices described in patent # 5,557,596.

C. Advantages of the invention over what has been done before.

The present invention gives larger readback signals in near-field optical recording devices. Also, it can make use of storage materials that don't necessarily exhibit large changes in reflectivity between their written and unwritten states. This new invention is not as susceptible to surface conditions as the devices described in patent # 5,557,596. It also has more design flexibility and possibly better robustness than the electron-beam readback devices described in patent # 5,557,596.

D. Description of the construction and operation of the invention (include appropriate schematic, block, & timing diagrams; drawings; samples; graphs; flowcharts; computer listings; test results; etc.)

Incone embodiment, the storage medium is a diode. One layer of the diode is a material that can be changed between two or more states using a near-field optical source. We will call this the storage layer. The storage layer is in contact with another material or materials with which it forms a diode. The diode can be of any type that provides a built-in field for separating charge carriers. For example, the diode can be a pn-junction, pin-junction, or Schottky barrier depending on the material(s) used. A bit is written by locally altering the state of the storage layer with the aid of a near-field optical source. The different states of the storage material must be such that they provide a contrast in the bit detection ("read") mechanism described below. In one embodiment, the storage layer is a phase-change material similar to those currently used in optical recording. These materials can be reversibly changed from crystalline to amorphous by applying heat with the right temperature vs. time profile. The near-field optical source can be used for this purpose. The storage layer need not be a "phase-change" material, however. Any material that can be locally changed from one state to another state by means of a near-field optical source can be used. The near-field source need not operate in isolation to affect the transition from one state to another. It can also be used in conjunction with some other energy source. For example a resistive heater or applied electric field could be used to bias a large area of the storage medium while the near-field source locally affected a phase-change.

To read a bit, a near-field optical source is used to locally excite charge carriers in one of the layers of the diode. If carriers are excited in the storage layer, the number of carriers created (the "generation efficiency") will depend on the state of the storage layer in the region where photons

from the near-field source are incident. The present that determine the generation efficiency includes a band structure of the storage layer. Some fraction of the generated carriers of one sign (enter electrons or holes) will be swept across the diode interface under the influence of the built-in field and any applied field. The current that results from carriers passing across the diode interface can be monitored to determine the state of the area on which the read photons are incident. The fraction of generated carriers that makes it across the diode interface (the "collection efficiency") is dependent upon the recombination rate in and around the area on which the read photons are incident, the effect of the bit on the built-in fields, etc. Thus, contrast in the current generated across the diode by the read photons can depend on both the local generation efficiency and the local collection efficiency. Both of these factors are influenced by the state of the region upon which the read photons are incident.

The generation and collection efficiency for carriers generated in the Layer Adjacent to the Storage Layer (LASL) can also be influenced by the presence of a bit in the neighboring storage area. Carriers can be generated in the LASL if it is the layer closest to the near-field source. Alternatively, carriers can be generated in the LASL, even if the storage layer is closest to the source, if the storage layer is sufficiently transparent to the read beam. In this case, the number of carriers generated in the LASL will depend on the number of read photons that make it through the storage layer. Thus, contrast in the read signal can be obtained by using the storage layer as a state-sensitive variable absorber. In this case, the storage layer may not itself form part of the diode structure. The transmission of this absorber can depend upon whether the beam is passing through a written or unwritten region. Alternatively, contrast in the generation rate of carriers in the LASL can arise due to differences in the electric field in the LASL due to the presence or absence of a bit in the neighboring storage layer. One way in which an electric field can influence the generation rate for free carriers is by reducing the geminate recombination rate. The collection efficiency for carriers generated in the LASL can be also be influenced by the presence or absence of a bit in the neighboring storage layer via changes in the electric field. In addition, this collection efficiency can be influenced by changes in recombination rate due to the presence or absence of a bit in the neighboring storage layer (e.g. an amorphous bit could locally increase the interface recombination velocity at the storage layer/LASL interface). Again, differences in the collection efficiency of carriers created by the read beam provide contrast in the signal current generated across the diode.

It may be advantageous to cover the storage layer with a protective layer. During the write process, this protective layer could help to prevent chemical changes such as oxidation or thermomechanical changes such as bump or pit formation. It is possible that the LASL could serve as the protective layer as long as it is thin enough to allow writing of small bits. The protective layer may be merely a passivation layer, or it may be a conducting transparent electrode that is used to collect the photogenerated carriers.

The presence of electrodes on both the top and bottom surfaces of the storage layer and a possible LASL may offer advantages in device design. For example, uniform top and bottom electrodes will enhance the uniformity of the biasing field formed between the electrode and the storage layer. A back electrode could be present either on the side of the substrate opposite the optical sources (if a conducting substrate is used), or the back electrode could be on top of the substrate (if an electrically isolated substrate is used that provides mechanical support, but is not part of the electrical device *per se*. A top electrode could, in an optical access scheme, cover the entire top surface of the device.

It may be advantageous to cover the storage layer with a layer that enhances the thermal properties of the overall storage medium. E.g., if the storage layer is a phase-change material then it may be desirable for it to be in contact with a layer that aids in thermal quenching when trying to amorphize it. Alternatively or in conjunction with a cover layer it may be desirable to have a layer undemeath the storage layer or LASL that improves thermal properties such as the ability to quench (and amorphize) the storage layer. An underlayer may also enhance the robustness of the device by preventing interdiffusion between the storage layer and the substrate material, or by discouraging delamination or dewetting of the storage layer (or LASL) from the substrate.

It may be advantageous to cover the storage layer with a layer that enhances optical properties such as an anti-reflection coating. For example, this could be used to increase the amount of light from the near field source that is absorbed in the storage layer or LASL. Alternatively, or in conjunction with a cover layer, a layer underneath the storage layer or LASL could be used to enhance the optical properties.

By monitoring the collection efficiency of a diode structure, it may be possible to control the separation of a plate containing the storage layer and diode structure from the optical sources. Alternatively, it may be possible to control this separation by monitoring the light reflected back into the near-field optical source, or by using a combination of both techniques. It may be advantageous to provide tracking and sector reference marks on the media layer surface by providing areas of contrasting reflectivity or diode collection efficiency.

When reading back signals from the media, it may be advantageous to use the near-field optical source in a constant flux mode, with the light source on steadily and the sampling window provided by translation or rotation of the media underneath the source. Alternatively, it might be preferable to pulse the optical source or otherwise modulate it in order to use a phase- and/or frequency-selective signal-to-noise enhancement technique in the diode signal amplifier electronics.